

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-89 (Canceled)

Claim 90 (Currently amended): An electronic component comprising:

a substrate including a conductive ~~[[area]]~~ element disposed at a surface of the substrate; and

a resilient, conductive contact structure comprising a base portion electrically coupled to the conductive ~~area of~~ element at the surface of the substrate, a tip portion displaced a vertical distance away from the surface of the substrate ~~and the conductive area~~, and a beam portion between the base portion and the tip portion, the base portion comprising a plurality of layers, a first of the layers comprising a first material and a second of the layers comprising a second material, the first material being different than the second material,

wherein a length of the beam portion extends from the base portion to the tip portion, and a width of the beam portion decreases along the length from the base portion to the tip portion.

Claim 91 (Currently amended): The electronic component of claim 90 further comprising:

a connecting layer coupling the conductive ~~[[area]]~~ element to internal circuitry within the electronic component;

a passivation layer disposed on ~~[[a]]~~ the surface of the substrate, the passivation layer having an opening at the conductive ~~area of the substrate~~ element; and

at least one electrically conductive layer disposed on the passivation layer and on the conductive ~~area of the substrate~~ element,

wherein the base portion of the contact structure is electrically coupled through the at least one electrically conductive layer to the conductive ~~area of the substrate~~ element.

Claim 92 (Currently amended): The electronic component of claim 91, wherein the conductive ~~[[area]]~~ element comprises a terminal.

Claim 93 (Canceled)

Claim 94 (Previously presented): The electronic component of claim 91, wherein the tip portion comprises a pointed end.

Claim 95 (Previously presented): The electronic component of claim 91, wherein the substrate comprises a semiconductor device.

Claim 96 (Previously presented): The electronic component of claim 91, wherein the contact structure comprises the plurality of layers.

Claim 97 (Previously presented): The electronic component of claim 96, wherein ones of the layers comprise metals.

Claim 98 (Previously presented): The electronic component of claim 91 further comprising a plurality of the contact structures, wherein adjacent contact structures are spaced between 2.5 microns and 2000 microns from each other.

Claim 99 (Previously presented): The electronic component of claim 91, wherein the tip portion comprises a beveled peripheral edge.

Claim 100 (Previously presented): The electronic component of claim 91, wherein the beam portion comprises a triangular shape.

Claim 101 (Previously presented): The electronic component of claim 100, wherein the tip portion comprises a quadrilateral shape.

Claim 102 (Previously presented): The electronic component of claim 101, wherein the tip portion comprises a rectangular shape.

Claim 103 (Currently amended): The electronic component of claim 91, wherein the length of the beam portion comprises a generally linear slope from the base portion to the tip portion, the slope having an angle greater than zero with respect to the surface of the substrate at which the conductive element is disposed.

Claim 104 (Currently amended): An electronics system comprising:

a first substrate including a conductive [[area]] element disposed at a surface of the first substrate;

a resilient conductive contact structure comprising a base portion electrically coupled to the conductive [[area]] element of the first substrate, one and only one tip portion displaced a vertical distance away from the surface of the first substrate, and one and only one beam portion between the base portion and the tip portion, wherein a length of the beam portion extends from the base portion to the tip portion, and a width of the beam portion decreases along the length from the base portion to the tip portion; and

a second substrate including a conductive contact element in physical contact with the one and only one tip portion of the contact structure and deflecting the contact structure, the contact structure exerting a force against the contact element due to the resiliency of the contact structure.

Claim 105 (Currently amended): The electronics system of claim 104 further comprising:

a connecting layer coupling the conductive [[area]] element to internal circuitry within the first substrate;

a passivation layer disposed on [[a]] the surface of the first substrate, the passivation layer having an opening at the conductive [[area]] element of the first substrate; and

at least one electrically conductive layer disposed on the passivation layer and on the conductive [[area]] element of the first substrate,

wherein the contact structure is electrically coupled through the at least one electrically conductive layer to the conductive [[area]] element of the first substrate.

Claim 106 (Currently amended): The electronics system of claim 105, wherein the conductive [[area]] element comprises a terminal.

Claim 107 (Canceled)

Claim 108 (Previously presented): The electronics system of claim 105, wherein the tip portion comprises a pointed end.

Claim 109 (Previously presented): The electronics system of claim 105, wherein the first substrate comprises a semiconductor device.

Claim 110 (Previously presented): The electronics system of claim 105, wherein the contact structure comprises a metal layer.

Claim 111 (Previously presented): The electronics system of claim 110, wherein the contact structure comprises a plurality of metal layers.

Claim 112 (Previously presented): The electronics system of claim 105 further comprising a plurality of the contact structures, wherein adjacent contact structures are spaced between 2.5 microns and 2000 microns from each other.

Claim 113 (Previously presented): The electronics system of claim 105, wherein the tip portion comprises a beveled peripheral edge.

Claim 114 (Previously presented): The electronics system of claim 105, wherein the beam portion comprises a triangular shape.

Claim 115 (Previously presented): The electronics system of claim 114, wherein the tip portion comprises a quadrilateral shape.

Claim 116 (Previously presented): The electronics system of claim 115, wherein the tip portion comprises a rectangular shape.

Claim 117 (Currently amended): The electronics system of claim 105, wherein the length of the beam portion comprises a generally linear slope from the base portion to the tip portion, the slope having an angle greater than zero with respect to the surface of the substrate at which the conductive element is disposed.

Claim 118 (Previously presented): The electronic component of claim 90, wherein the plurality of layers comprise an electrically conductive seed layer and a layer of structural material disposed on the seed layer.

Claim 119 (Previously presented): The electronic component of claim 90, wherein the beam portion comprises the plurality of layers of materials.

Claim 120 (New): The electronic component of claim 90, wherein the vertical distance is perpendicular to the surface of the substrate at which the conductive element is disposed.

Claim 121 (New): The electronic component of claim 90, wherein the tip is disposed above the surface of the substrate at which the conductive element is disposed.

Claim 122 (New): The electronics system of claim 104, wherein the vertical distance is perpendicular to the surface of the substrate at which the conductive element is disposed.

Claim 123 (New): The electronics system of claim 104, wherein the tip is disposed above the surface of the substrate at which the conductive element is disposed.